

**PROD** 

V<sub>DS</sub> (V) R<sub>DS(on)</sub> (C

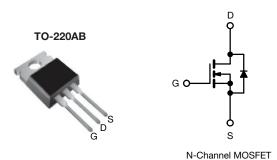
Q<sub>q</sub> max.

Q<sub>gs</sub> (nC)

Q<sub>gd</sub> (nC)

Configuration

## **Power MOSFET**



UCT SUMMARY						
	500					
(2)	V <sub>GS</sub> = 10 V	3.0				
(nC)	24					
	2.2					

13

Single

#### **FEATURES**

- Dynamic dV/dt rating
- Repetitive avalanche rated
- Fast switching
- · Ease of paralleling
- · Simple drive requirements
- Material categorization: for definitions of compliance please see <a href="https://www.vishav.com/doc?99912"><u>www.vishav.com/doc?99912</u></a>

#### Note

\* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

## **DESCRIPTION**

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	IRF820PbF			
Lead (Pb)-free and halogen-free	IRF820PbF-BE3			

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V <sub>DS</sub>	500	V	
Gate-source voltage			$V_{GS}$	± 20	v	
Continuous drain current	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C		2.5		
Continuous drain current		T <sub>C</sub> = 100 °C	I <sub>D</sub>	1.6	Α	
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	8.0		
Linear derating factor				0.40	W/°C	
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	210	mJ	
Repetitive avalanche current a			I <sub>AR</sub>	2.5	А	
Repetitive avalanche energy <sup>a</sup>			E <sub>AR</sub>	5.0	mJ	
Maximum power dissipation $T_C = 25  ^{\circ}C$			$P_{D}$	50	W	
Peak diode recovery dV/dt c			dV/dt	3.5	V/ns	
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C	
Soldering recommendations (peak temperature) d For 10 s				300		
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
Mounting torque				1.1	N·m	

### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 60 mH,  $R_q$  = 25  $\Omega$ ,  $I_{AS}$  = 2.5 A (see fig. 12)
- c.  $I_{SD} \le 2.5$  A,  $dI/dt \le 50$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_{J} \le 150$  °C
- d. 1.6 mm from case



# Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62			
Case-to-sink, flat, greased surface	R <sub>thCS</sub>	0.50	-	°C/W		
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	2.5			

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				L	L		
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA		500	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I <sub>D</sub> = 1 mA	-	0.59	-	V/°C
Gate-source threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA		-	4.0	V
Gate-source leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	_	± 100	nA
		V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V		-	-	25	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 400 V	', V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	250	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 1.5 A <sup>b</sup>	-	-	3.0	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 50 V, I <sub>D</sub> = 1.5 A	1.5	-	-	S
Dynamic						•	
Input capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$	-	360	-	
Output capacitance	C <sub>oss</sub>	1	$V_{DS} = 25 \text{ V},$	-	92	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1	.0 MHz, see fig. 5	-	37	-	1
Total gate charge	Qg			-	-	24	nC
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	$I_D = 2.1 \text{ A}, V_{DS} = 400 \text{ V},$ see fig. 6 and 13 b	-	-	3.3	
Gate-drain charge	Q <sub>gd</sub>		occ lig. o and ro	=	-	13	
Turn-on delay time	t <sub>d(on)</sub>	$V_{DD}$ = 250 V, $I_D$ = 2.1 A, $R_g$ = 18 $\Omega$ , $R_D$ = 100 $\Omega$ , see fig. 10 $^{\rm b}$		-	8.0	-	- ns
Rise time	t <sub>r</sub>			-	8.6	-	
Turn-off delay time	t <sub>d(off)</sub>			=	33	-	
Fall time	t <sub>f</sub>			-	16	-	
Gate input resistance	Rg	f = 1 MHz, open drain		1.8	-	12.6	Ω
Internal drain inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	- nH
Internal source inductance	L <sub>S</sub>			-	7.5	-	
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous source-drain diode current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	2.5	_
Pulsed diode forward current <sup>a</sup>	I <sub>SM</sub>			-	-	8.0	- A
Body diode voltage	V <sub>SD</sub>	$T_J = 25  ^{\circ}\text{C},  I_S = 2.5  \text{A},  V_{GS} = 0  \text{V}^{ \text{b}}$		-	-	1.6	V
Body diode reverse recovery time	t <sub>rr</sub>	T _ 05 °C !	= 0.1 A dl/dt 100 A/c-	-	260	520	ns
Body diode reverse recovery charge	Q <sub>rr</sub>	$T_J = 25  ^{\circ}\text{C}, I_F = 2.1  \text{A}, dI/dt = 100  \text{A/}\mu\text{s}$		-	0.7	1.4	nC
Forward turn-on time	t <sub>on</sub>	Intrinsic to	n-on is dominated by L <sub>S</sub> and L <sub>D</sub> )				

## Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width  $\leq 300 \ \mu s$ ; duty cycle  $\leq 2 \ \%$



## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

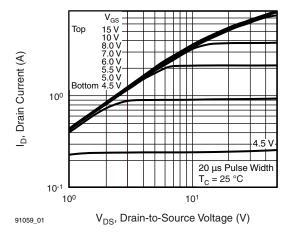


Fig. 1 - Typical Output Characteristics,  $T_C = 25$  °C

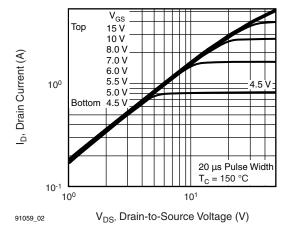


Fig. 2 - Typical Output Characteristics,  $T_C = 150$  °C

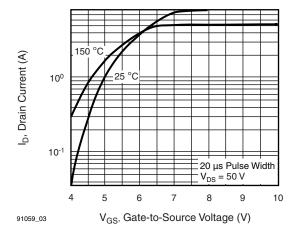


Fig. 3 - Typical Transfer Characteristics

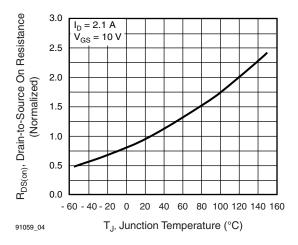


Fig. 4 - Normalized On-Resistance vs. Temperature

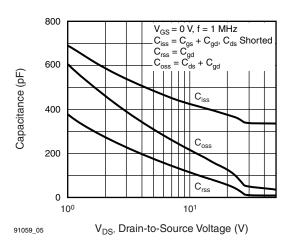


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

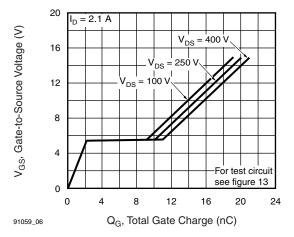


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



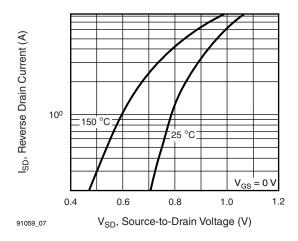


Fig. 7 - Typical Source-Drain Diode Forward Voltage

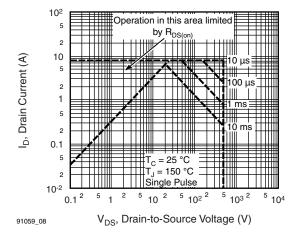


Fig. 8 - Maximum Safe Operating Area

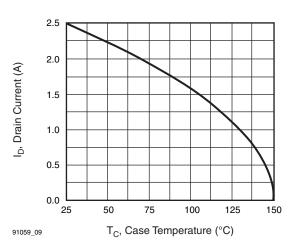


Fig. 9 - Maximum Drain Current vs. Case Temperature

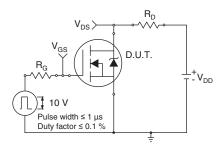


Fig. 10a - Switching Time Test Circuit

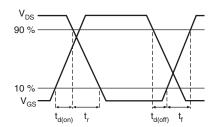


Fig. 10b - Switching Time Waveforms

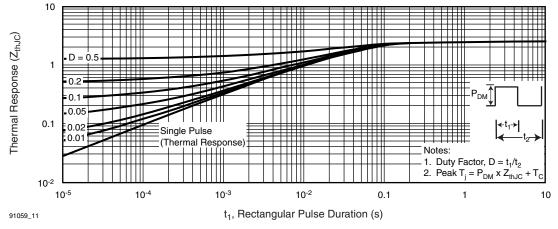


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



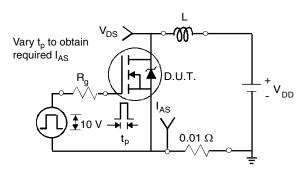


Fig. 12a - Unclamped Inductive Test Circuit

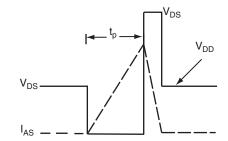


Fig. 12b - Unclamped Inductive Waveforms

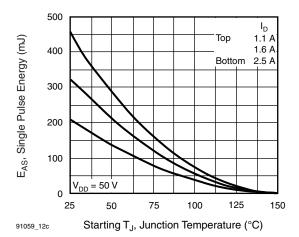


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

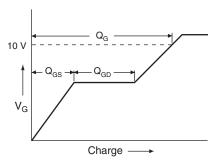


Fig. 13a - Basic Gate Charge Waveform

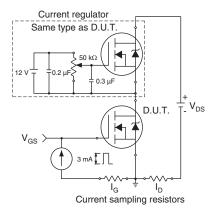
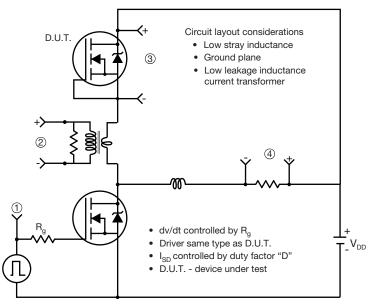


Fig. 13b - Gate Charge Test



#### Peak Diode Recovery dv/dt Test Circuit



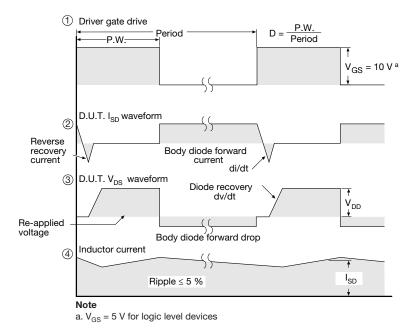


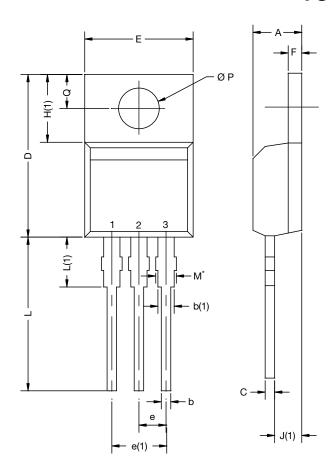
Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?91059">www.vishay.com/ppg?91059</a>.





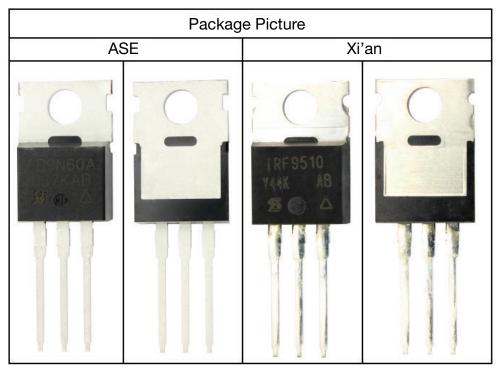
# TO-220-1



DIM	MILLIN	IETERS	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.	
Α	4.24	4.65	0.167	0.183	
b	0.69	1.02	0.027	0.040	
b(1)	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.33	15.85	0.564	0.624	
E	9.96	10.52	0.392	0.414	
е	2.41	2.67	0.095	0.105	
e(1)	4.88	5.28	0.192	0.208	
F	1.14	1.40	0.045	0.055	
H(1)	6.10	6.71	0.240	0.264	
J(1)	2.41	2.92	0.095	0.115	
L	13.36	14.40	0.526	0.567	
L(1)	3.33	4.04	0.131	0.159	
ØР	3.53	3.94	0.139	0.155	
Q	2.54	3.00	0.100	0.118	
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031					

## Note

 $\bullet$   $M^{\star}=0.052$  inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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